Kingbright

2.0x1.25mm SMD CHIP LED LAMP

Part Number: KP-2012SECK-J3 Hyper Red

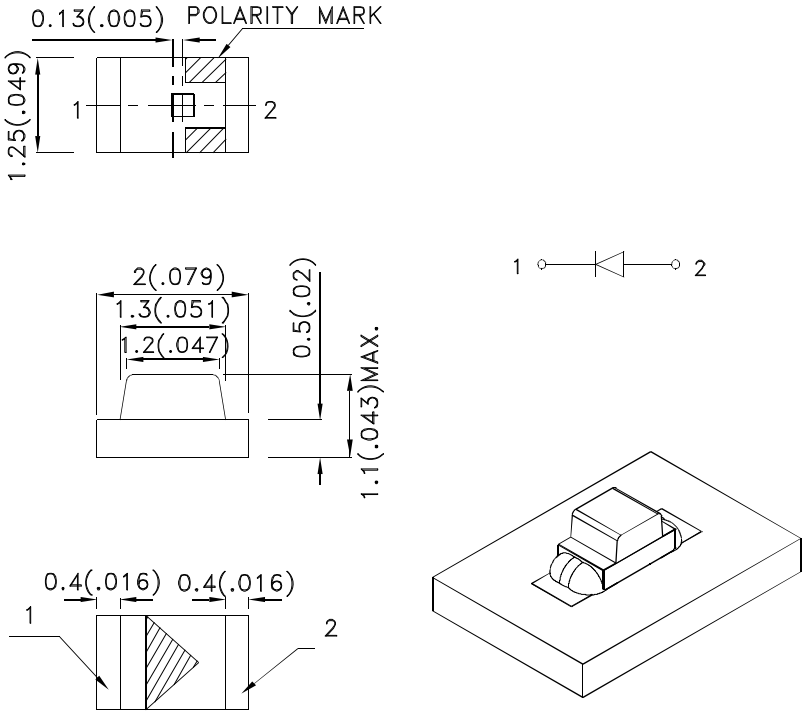
Features

- 2.0mmx1.25mm SMT LED,1.1mm thickness.
- Low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- Package : 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Hyper Red device is based on light emitting diode chip made from AlGaInP.

Package Dimensions



Notes:
1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.1(0.004") unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
KP-2012SECK-J3	Hyper Red (AlGaInP)	Water Clear	700	1100	120°
			*200	*350	

Notes:
1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.
*Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

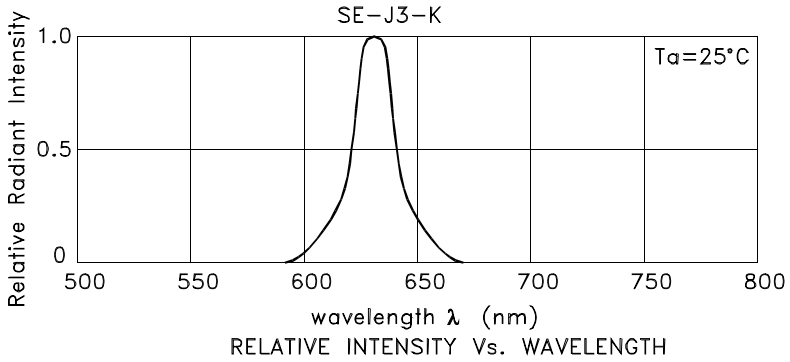
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	640		nm	I_F=20mA
λD [1]	Dominant Wavelength	Hyper Red	625		nm	I_F=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red	20		nm	I_F=20mA
C	Capacitance	Hyper Red	27		pF	V_F=0V;f=1MHz
V_F [2]	Forward Voltage	Hyper Red	2.2	2.8	V	I_F=20mA
I_R	Reverse Current	Hyper Red		10	uA	V_R=5V

Notes:
1.Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.
3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

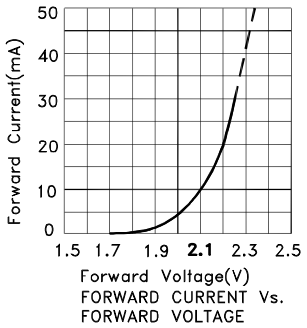
Parameter	Hyper Red	Units
Power dissipation	84	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating Temperature	-40°C To +85°C	
Storage Temperature	-40°C To +85°C	

Note:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

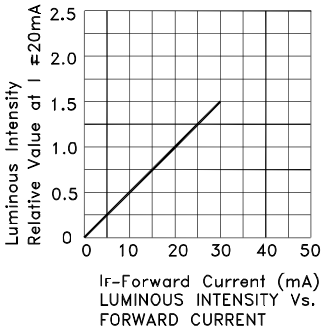


RELATIVE INTENSITY Vs. WAVELENGTH

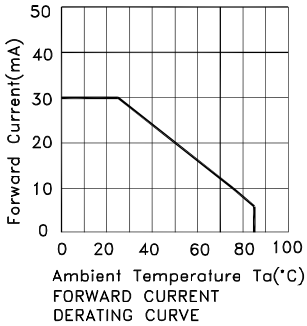
Hyper Red **KP-2012SECK-J3**



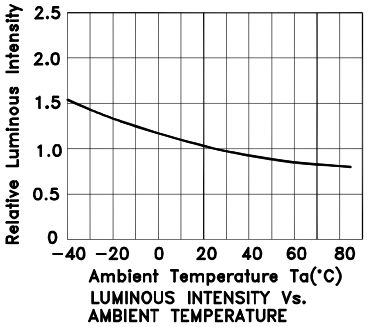
FORWARD CURRENT Vs.
FORWARD VOLTAGE



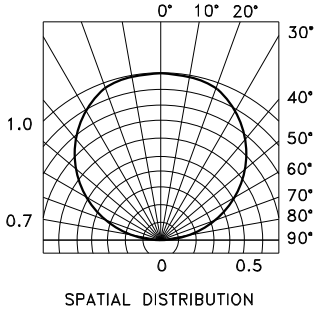
LUMINOUS INTENSITY Vs.
FORWARD CURRENT



FORWARD CURRENT
DERATING CURVE



LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

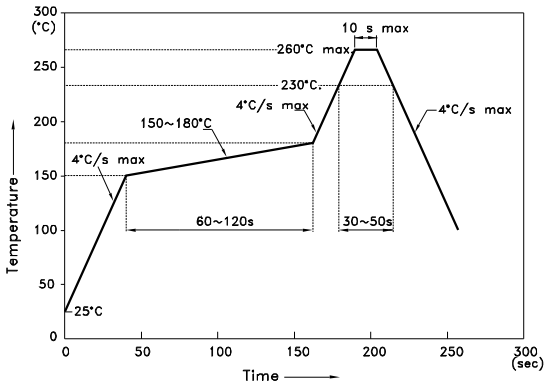


SPATIAL DISTRIBUTION

KP-2012SECK-J3

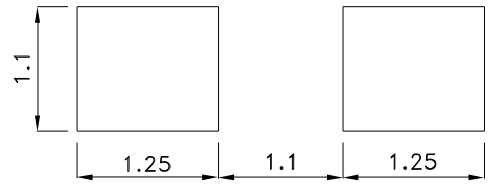
Reflow soldering is recommended and the soldering profile is shown below.
Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.

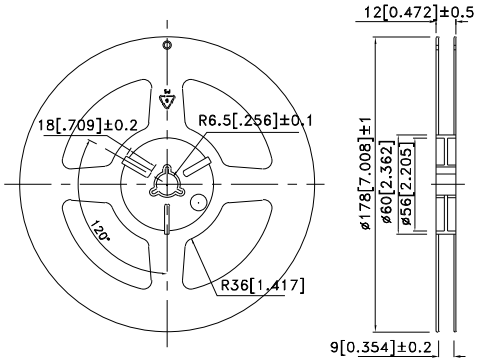


NOTES:
1. We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

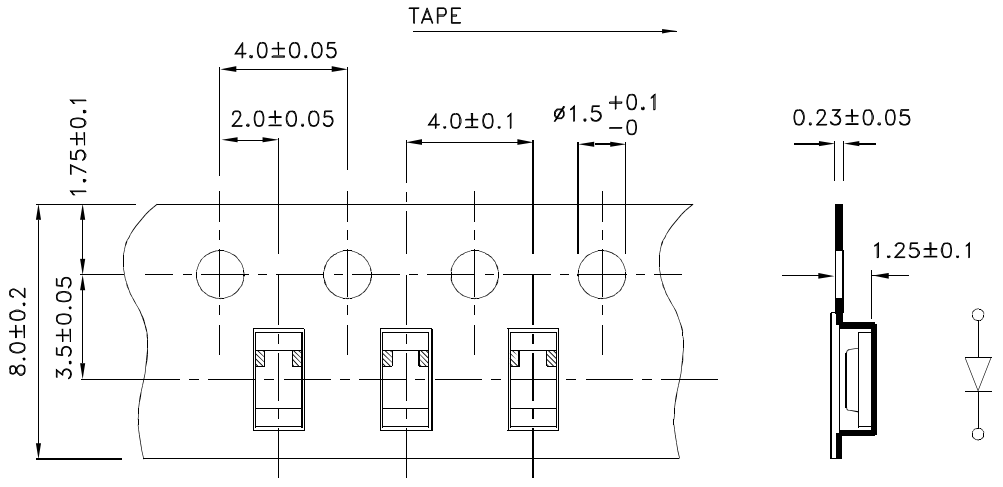
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



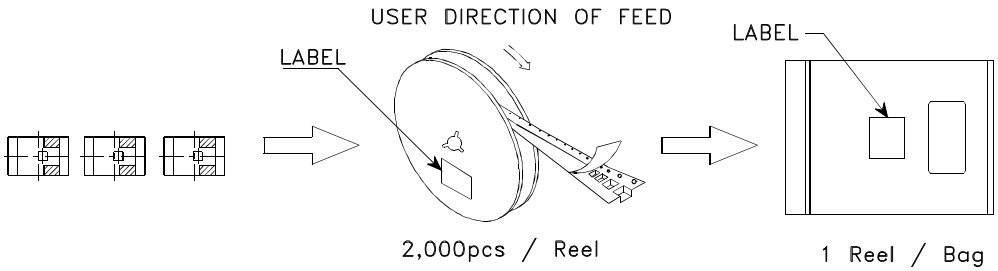
Reel Dimension

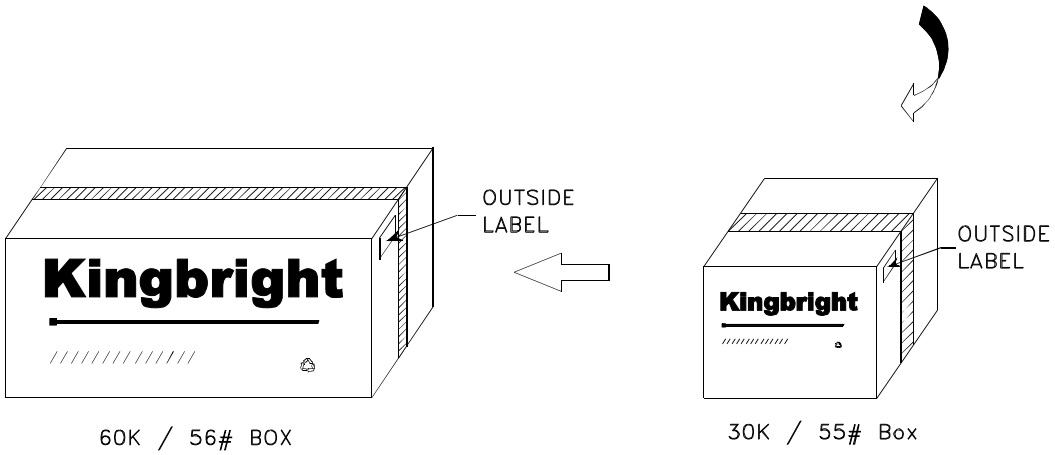


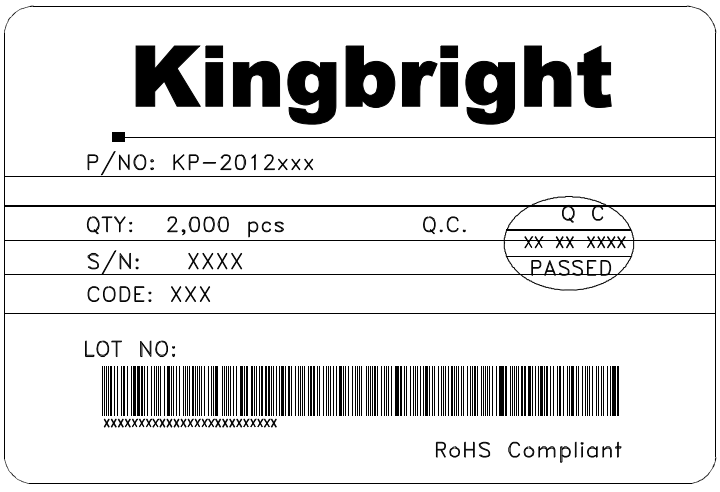
Tape Dimensions (Units : mm)



PACKING & LABEL SPECIFICATIONS **KP-2012SECK-J3**







Detailed application notes are listed on our website.
http://www.kingbright.com/application_notes